

**Amendments to the Claims:**

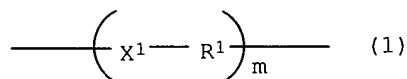
This listing of claims will replace all prior versions and listings of claims in the application:

1. (Original) A resin composition used as an adhesive bonding a semiconductor chip or a heat dissipating member comprising a filler (A), the following compound (B) and a thermal radical initiator (C), and substantially not containing a photo polymerization initiator:

Compound (B):

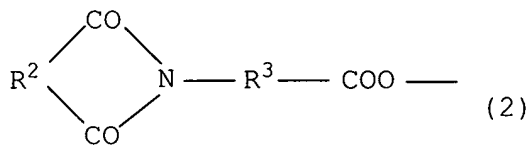
a compound containing a structure represented by the following formula (1) in a main chain and having at least one functional group represented by the following formula (2):

Formula (1):



wherein  $\text{X}^1$  is  $\text{---O---}$ ,  $\text{---COO---}$  or  $\text{---OCOO---}$ ;  $\text{R}^1$  is a hydrocarbon group having 1 to 6 carbons; "m" is an integer of 1 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other;

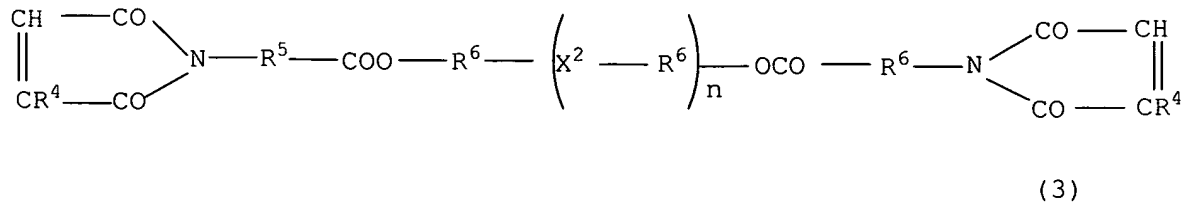
Formula (2):



wherein  $\text{R}^2$  is  $\text{---C}_2\text{H}_2\text{---}$  or  $\text{---C}_3\text{H}_4\text{---}$ ;  $\text{R}^3$  is a hydrocarbon group having 1 to 11 carbons; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

2. (Original) A resin composition according to Claim 1, wherein the filler (A) is silver powder.
3. (Amended) A resin composition according to Claim 1 ~~or 2~~, wherein X<sup>1</sup> of the compound (B) is -O-.
4. (Amended) A resin composition according to ~~any of Claims 1 to 3~~ Claim 1, wherein R<sup>1</sup> of the compound (B) is a hydrocarbon group having 3 to 6 carbons.
5. (Original) A resin composition according to Claim 4, wherein R<sup>1</sup> of the compound (B) is at least one selected from the group consisting of -C<sub>3</sub>H<sub>6</sub>- and -C<sub>4</sub>H<sub>8</sub>-.
6. (Amended) A resin composition according to ~~any of Claims 1 to 5~~ Claim 1, wherein R<sup>2</sup> is -C<sub>2</sub>H<sub>2</sub>- and R<sup>3</sup> is -CH<sub>2</sub>- in the compound (B).
7. (Amended) A resin composition according to ~~any of Claims 1 to 6~~ Claim 1, wherein the compound (B) has two functional groups represented by the formula (2).
8. (Amended) A resin composition according to ~~any of Claims 1 to 7~~ Claim 1, wherein the compound (B) is a ~~bismaleimide~~ bis-maleimide compound (B') represented by the following formula (3):

Formula (3):



wherein X<sup>2</sup> is -O-, -COO- or -OCOO-; each R<sup>4</sup> is hydrogen atom or a methyl group; each R<sup>5</sup> is a hydrocarbon group having 1 to 11 carbons; each R<sup>6</sup> is a hydrocarbon group having 3 to 6 carbons; "n" is an integer of 1 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

9. (Amended) A resin composition according to Claim 8, wherein X<sup>2</sup> of the ~~bismaleimide~~ bis-maleimide compound (B') represented by the formula (3) is -O-.

10. (Amended) A resin composition according to Claim 8 ~~or 9~~, wherein R<sup>5</sup> of the ~~bismaleimide~~ bis-maleimide compound (B') represented by the formula (3) is a hydrocarbon group not containing an aromatic group.

11. (Amended) A resin composition according to ~~any of Claims 8 to 10~~ Claim 8, wherein R<sup>5</sup> of the ~~bismaleimide~~ bis-maleimide compound (B') represented by the formula (3) has 1 to 5 carbons.

12. (Amended) A resin composition according to ~~any of Claims 8 to 11~~ Claim 8, wherein R<sup>5</sup> of the ~~bismaleimide~~ bis-maleimide compound (B') represented by the formula (3) is -CH<sub>2</sub>- or -C<sub>5</sub>H<sub>10</sub>-.

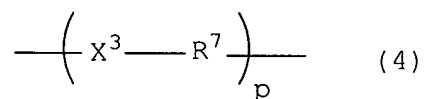
13. (Amended) A resin composition according to ~~any of Claims 8 to 12~~ Claim 8, wherein R<sup>6</sup> of the ~~bismaleimide~~ bis-maleimide compound (B') represented by the formula (3) is at least one selected from the group consisting of -C<sub>3</sub>H<sub>6</sub>- and -C<sub>4</sub>H<sub>8</sub>-.

14. (Amended) A resin composition according to ~~any of Claims 1 to 13~~ Claim 1, further comprising the following compound (D):

Compound (D):

a compound containing a structure represented by the formula (4) in a main chain and having at least one functional group having a polymerizable C-C unsaturated bond:

Formula (4):

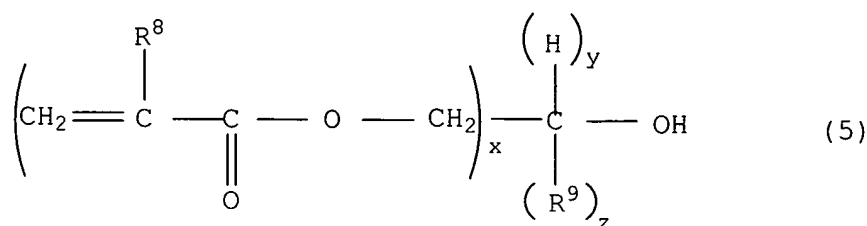


wherein X<sup>3</sup> is -O-, -COO- or -OCOO-; R<sup>7</sup> is a hydrocarbon group having 3 to 6 carbons; "p" is an integer of 1 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

15. (Amended) A resin composition according to ~~any of Claims 1 to 14~~ Claim 1, further containing the following acrylic ester compound (E):

Acrylic ester compound (E):

Formula (5):



wherein R<sup>8</sup> is hydrogen atom or a methyl group; R<sup>9</sup> is a hydrocarbon group having 1 to 3 carbons; "x", "y" and "z" are in the relationship expressed by (x+y+z)=3, 1≤x≤3, 0≤y≤2 and 0≤z≤2; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

16. (Amended) A resin composition according to ~~Claim 15~~ Claim 1, wherein R<sup>8</sup> of the acrylic ester compound (E) represented by the formula (5) is a methyl group.

17. (Amended) A resin composition according to ~~Claim 15~~ Claim 1, wherein R<sup>9</sup> of the acrylic ester compound (E) represented by the formula (5) is a methyl group.

18. (Amended) A resin composition according to ~~Claim 16~~ Claim 1, wherein R<sup>8</sup> is a methyl group, R<sup>9</sup> is a methyl group, and x=1, y=1, and z=1 in the acrylic ester compound (E) represented by the formula (5).

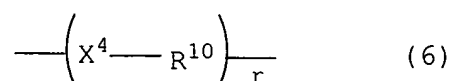
19. (Amended) A resin composition according to ~~Claim 16~~ Claim 1, wherein R<sup>8</sup> is a methyl group, x=2, y=1 and z=0 in the acrylic ester compound (E) represented by the formula (5).

20. (Amended) A resin composition according to any of ~~Claims 1 to 19~~ Claim 1, further comprising the following acrylamide compound (F):

Acrylamide compound (F):

a compound containing a structure represented by the following formula (6) in a main chain and having at least one functional group represented by the following formula (7):

Formula (6):



Formula (7):



wherein  $\text{X}^4$  is  $-\text{O}-$ ,  $-\text{COO}-$  or  $-\text{OCOO}-$ ;  $\text{R}^{10}$  is a hydrocarbon group having 3 to 6 carbons;  $\text{R}^{11}$  is hydrogen atom or a methyl group; "r" is an integer of 1 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

21. (Amended) A resin composition according to ~~Claim 20~~ Claim 20, wherein  $\text{R}^{10}$  of the structure represented by the formula ~~(6)~~ (5) of the acrylamide compound ~~(F)~~ (E) is at least one selected from the group consisting of  $-\text{C}_3\text{H}_6-$  and  $-\text{C}_4\text{H}_8-$ .

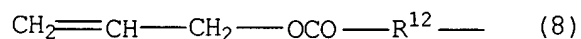
22. (Amended) A resin composition according to ~~Claim 20 or 21~~ Claim 20, wherein  $\text{X}^4$  of the structure represented by the formula ~~(6)~~ (5) of the acrylamide compound ~~(F)~~ (E) is  $-\text{O}-$ .

23. (Amended) A resin composition according to any of ~~Claims 1 to 22~~ Claim 1, further containing the following allyl ester compound (G):

Allyl ester compound (G):

a compound having at least one functional group represented by the following formula (8):

Formula (8):

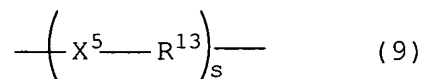


wherein R<sup>12</sup> is a hydrocarbon group having 2 to 8 carbons.

24. (Original) A resin composition according to Claim 23, wherein R<sup>12</sup> of the structure represented by the formula (8) of the allyl ester compound (G) does not contain an aromatic group.

25. (Amended) A resin composition according to ~~Claim 23 or 24~~ Claim 23, wherein the allyl ester compound (G) contains a structure represented by the following formula (9):

Formula (9):



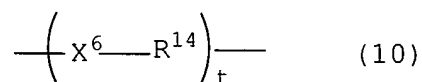
wherein  $X^5$  is  $-O-$ ,  $-COO-$  or  $-OCOO-$ ;  $R^{13}$  is a hydrocarbon group having 3 to 6 carbons; "s" is an integer of 1 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

26. (Amended) A resin composition according to any of ~~Claims 1 to 25~~ Claim 1, further containing the following compound (H):

Compound (H):

a compound derived from a hydrocarbon having at least one C-C unsaturated bond in one molecule, which has a number average molecular weight of 500 to 5,000, contains a structure represented by the following formula (10) at its modified position, and has at least one functional group having a polymerizable C-C unsaturated bond:

Formula (10):



wherein  $X^6$  is  $-O-$ ,  $-COO-$  or  $-OCOO-$ ;  $R^{14}$  is a hydrocarbon group having 3 to 6 carbons; "t" is an integer of 1 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other.

27. (Original) A resin composition according to Claim 26, wherein  $X^6$  is  $-O-$  and  $R^{14}$  is  $C_4H_8$  in the structure represented by the formula (10) of the compound (H).



28. (Amended) A resin composition according to Claim 26 ~~or 27~~, wherein a hydrocarbon led to the compound (H) and having at least one C-C unsaturated bond in one molecule is a butadiene polymer.
29. (Amended) A resin composition according to Claim 26 ~~or 27~~, wherein a hydrocarbon led to the compound (H) and having at least one C-C unsaturated bond in one molecule is an isoprene polymer.
30. (Amended) A resin composition according to ~~any of Claims 26 to 29~~ Claim 26, wherein the polymerizable C-C unsaturated bond of the compound (H) is a (meth)acryloyl group.
31. (Amended) A resin composition according to ~~any of Claims 1 to 30~~ Claim 1, further containing a reactive diluent (I).
32. (Original) A resin composition according to Claim 31, wherein the reactive diluent (I) is a vinyl compound which is in liquid form at room temperature other than the compounds (D) to (H).
33. (Original) A resin composition according to Claim 32, wherein the vinyl compound is a compound containing at least one (meth)acryloyl group.
34. (Amended) A resin composition according to ~~any of Claims 1 to 33~~ Claim 1, further containing a silane-based coupling agent (J).
35. (Original) A resin composition according to Claim 34, wherein the coupling agent (J) is a silane coupling agent having an S-S bond.

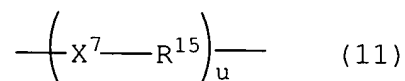
36. (Amended) A resin composition according to Claim 34 ~~or 35~~, wherein the coupling agent (J) further contains a silane coupling agent having a glycidyl group.

37. (Amended) A resin composition according to ~~any of Claims 1 to 36~~ Claim 1, containing a compound (K) having a glycidyl group other than the silane coupling agent having a glycidyl group.

38. (Amended) A resin composition according to ~~any of Claims 1 to 37~~ Claim 1, further containing the following compound (L) and the following compound (M):

Compound (L):

a compound containing the following structure represented by the formula (11) in a main chain and having at least one glycidyl group:



wherein  $X^7$  is  $-O-$ ,  $-COO-$  or  $-OCOO-$ ;  $R^{15}$  is a hydrocarbon group having 3 to 6 carbons; "u" is an integer of 2 or more and 50 or less; and if the formula contains two or more parts which are denoted by the same symbol, each of them may be the same or different from each other;

Compound (M):

a compound having a functional group which can react with the glycidyl group of the compound (L).

39. (Amended) A compound according to Claim 38, wherein the repeating unit ( $X^7-R^{15}$ ) of the compound (L) is the same as the repeating unit ( $X^1-R^1$ ) of the compound (B) (M).

40. (Amended) A semiconductor device ~~produced by using the resin composition according to any of Claims 1 to 39~~ containing the resin composition according to Claim 1 as a die attach material.

41. (Amended) A semiconductor device ~~produced by using the resin composition according to any of Claims 1 to 39~~ containing the resin composition according to Claim 1 as a material for bonding a heat dissipating member.